

# LEAD FREE SOLDER PASTE

## CW Cleanable type

Excellent cleaning qualities.

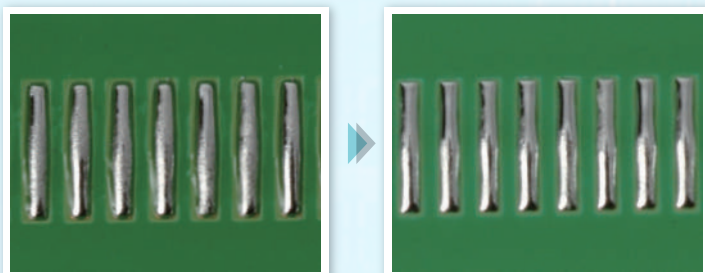
## Fine Solder



## Product Features

### ■ Excellent cleaning performance

Compatible with various types of cleaning agents, including high grade alcohol-based types as well as halogenated hydrocarbon-based types.



#### ■ Test conditions

Cleaning agent : Asahi Clean AK-225AES    Cleaning time : 1 minute  
temperature : 15°C    Cleaning method : Immerse and shake

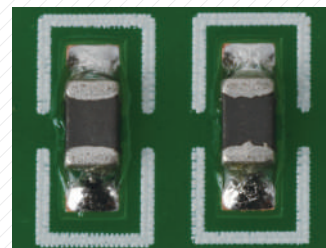
### ■ Maintaining a high level of reliability and workability

A cleanable solder paste, but maintaining the same level of reliability and workability as non cleanable solder paste.



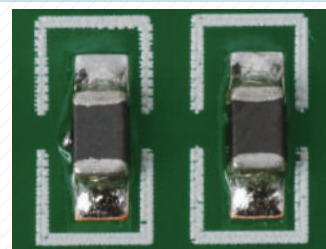
### FLF01-CW

No solder balls formed,  
ensuring excellent  
solderability.



Equivalent product from  
other manufacturers.

Solder balls formed  
because of cleaning required.



Items	FLF01-CW	Test method
Alloy composition	Sn96.5%-Ag3.0%-Cu0.5%	JIS Z3282
Solidus temperature	Approx. 217°C	JIS Z3282
Liquidus temperature	Approx. 219°C	JIS Z3282
Particle size	20~38μm (Type4)	JIS Z3284(J-STD-005)
Flux content	10.50%	JIS Z3197
Halide content	0.03%	JIS Z3197
Viscosity	190Pa·s	JIS Z3284
Thixotropy index	0.53	JIS Z3284
Copper plate corrosion test	Pass	JIS Z3197
Insulation resistance test (85°C 85%RH 168hr)	> 1.0×10 <sup>9</sup> Ω	JIS Z3197
Migration test (85°C 85%RH 1,000hr)	Pass	JIS Z3197
Spread rate	86%	JIS Z3197

